

Click here for the 3D model.

| Dimensions |  |
| :--- | :--- |
| Chip Size | 1210 |
| L | $3.3 \mathrm{~mm}+/-0.4 \mathrm{~mm}$ |
| W | $2.6 \mathrm{~mm}+/-0.3 \mathrm{~mm}$ |
| T | $2.5 \mathrm{~mm}+/-0.30 \mathrm{~mm}$ |
| B | $0.6 \mathrm{~mm}+/-0.25 \mathrm{~mm}$ |
|  |  |
| Packaging Specifications | T\&R, 180mm, Plastic Tape |
| Packaging | 1000 |
| Packaging Quantity |  |


$\left.$| General Information |  |
| :--- | :--- |
| Series | SMD HRA X7R |
| Style | SMD Chip |$\quad$| High Reliability Alternative (HRA), X-LEVEL, Flex |
| :--- |
| Termination, SnPb | \right\rvert\, | Description | No |
| :--- | :--- |
| RoHS | http://www.p65warnings.ca.gov. |


| Specifications |  |
| :--- | :--- |
| Capacitance | 4.7 uF |
| Measurement Condition | $10 \%$ |
| Capacitance Tolerance | 25 VDC |
| Voltage DC | 62.5 VDC |
| Dielectric Withstanding Voltage | $-55 /+125^{\circ} \mathrm{C}$ |
| Temperature Range | X 7 R |
| Temperature Coefficient | $15 \%, 1 \mathrm{kHz} 1.0 \mathrm{Vrms}$ |
| Capacitance Change with Reference <br> to $+25^{\circ} \mathrm{C}$ and O VDC Applied (TCC) | $3.5 \% 1 \mathrm{kHz} 1.0 \mathrm{Vrms}$ |
| Dissipation Factor | $3 \%$ Loss/Decade Hour: |
| Aging Rate | 106.4 MOhms |
| Insulation Resistance |  |

